


# MATERIAL DECLARATION SHEET



Material Number	CD214B-R Serial			
Product Line	Semiconductor Products			
Compliance Date	2005/03/02			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Solder wafer	Metal	1.552	Lead *2	7439-92-1	92.5	1.196	1.29
				Tin	7440-31-5	5	0.065	
				Silver	7440-22-4	2.5	0.032	
2	Dice	Metal	25.986	Silicon	7440-21-3	73.54	15.929	21.66
				Nickel	7440-02-0	1.99	0.431	
				Aluminum	7429-90-5	0.56	0.121	
				Lead*3	7439-92-1	14.80	3.205	
				Phosphorus	7723-14-0	0.249	0.054	
				Boron	7440-42-8	0.874	0.189	
				Trace metals	-	7.987	1.730	
3	Molding compound	Plastic	62.807	Silica	14808-60-7	70	36.637	52.34
				Epoxy Resin	29690-82-2	20	10.468	
				Phenol Resin	9003-35-4	8	4.187	
				Antimony trioxide	1309-64-4	2	1.047	
4	Lead Wire	Metal	29.555	Copper	7440-50-8	>99.0	24.383	24.63
				Misc., not to declare	-	<1.0	0.246	
5	Plating	Metal	0.1	Tin	7440-31-5	>99.0	0.083	0.08
				Misc., not to declare	-	<1.0	0.001	
		Total weight	120.0					

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This Document was updated on: 2015/11/03

## Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. \* : Excepted for RoHS 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead) ;
3. \* : Excepted for RoHS 7(c) I-Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors,e.g.piezoelectronic devices, or in a glass or ceramic matrix compound ;